

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	24024	438/15,25,55,64,106,118,618.ccls. or 257/81,700,e33.056,e33.066, e23.001,e23.067.ccls. or 216/13,17, 18.ccls. or 174/261,262,254-256. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S2	17619	S1 and @ad<"20030918"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:51
S3	1148	S2 and circuit near2 board and embed\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S4	815	S3 and (holes or through adj hole)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:52
S5	219	S4 and recess\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:53
S6	149	S5 and \$5conduct\$3 and insulat\$3 and fill\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:52
S7	9	S6 and (feed adj through or feedthrough)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12

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S8	9	(US-20030068877-\$ or US-20030067074-\$ or US-20040000710-\$).did. or (US-6797616-\$ or US-6239983-\$ or US-5886877-\$ or US-5081562-\$ or US-6774486-\$ or US-6806428-\$). did.	US-PGPUB; USPAT	OR	ON	2007/09/14 16:12
S9	32	S6 and (pre adj preg or prepreg)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S10	37	S6 and (embed\$4 near8 (component or device or module))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S11	10	S10 and (pre adj preg or prepreg)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S12	32	S11 or S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S13	10	S12 and (embed\$4 near8 (component or device or module))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S14	13	S13 S8	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12

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S15	9	S7 and (embed\$4 same (chip or component or device or module))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S16	22	S14 S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S17	16	S16 and adhesi\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:22
S18	15	S17 and pattern\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S19	36	("20020053465" "20030068852" "20030159852" "4246595" "4993148" "5042145" "5306670" "5353195" "5355102" "5248852" "5497033" "6154366" "6271469" "6475877" "6713859" "6284564" "6701614" "6876072").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S20	27	S19 and pattern\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S21	3	S20 and circuit near2 board and embed\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12

EAST Search History

S22	2	S21 and (pre adj preg or prepreg)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S23	7	S19 and (pre adj preg or prepreg)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S24	7	S23 and pattern\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:23
S25	2	S24 and circuit near2 board and embed\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:55
S26	2	(US-20020053465-\$).did. or (US-5248852-\$).did.	US-PGPUB; USPAT	OR	ON	2007/09/14 16:12
S27	20	S21 S26 S18	US-PGPUB; USPAT	OR	ON	2007/09/14 16:12
S28	20	S27 and @ad<"20030918"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 18:14
S29	30	S12 and (embed\$4 same (chip or component or device or module))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:22

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S30	7	S18 and (pre adj preg or prepreg)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:12
S31	131	S6 and adhesi\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 19:59
S32	110	S31 and (embed\$4 same (chip or component or device or module))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 20:52
S33	102	S32 and pattern\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 16:23
S34	7	(US-5985693-\$ or US-5840593-\$ or US-5654220-\$ or US-5048179-\$ or US-6350957-\$ or US-6239983-\$ or US-5886877-\$).did.	USPAT	OR	ON	2007/09/14 16:55
S35	1432	29/840.ccls.	USPAT	OR	ON	2007/09/14 16:55
S36	114	S35 and circuit near2 board and embed\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 20:55
S37	16	S36 and recess\$3 and pattern\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 19:50
S38	1	(US-5042145-\$).did.	USPAT	OR	ON	2007/09/14 16:59
S39	8	S34 S38	USPAT	OR	ON	2007/09/14 16:59

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S40	3	(US-20030159852-\$).did. or (US-20030159852-\$ or EP-367311-\$).did.	US-PGPUB; DERWENT	OR	ON	2007/09/14 18:13
S41	3	S34 S40	US-PGPUB; DERWENT	OR	ON	2007/09/14 18:13
S42	24	S14 S26 S39 S40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 18:14
S43	24	S42 and @ad<"20030918"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 18:15
S44	19	S43 and recess\$3 and pattern\$3 and circuit near2 board and embed\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 20:03
S45	5	S43 and (NOT S44)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 19:51
S46	2	(US-20030159852-\$).did. or (US-20030159852-\$).did.	US-PGPUB; DERWENT	OR	ON	2007/09/14 19:53
S47	10	(US-20030068877-\$ or US-20030067074-\$ or US-20040000710-\$).did. or (US-6806428-\$ or US-6797616-\$ or US-6774486-\$ or US-5985693-\$ or US-5840593-\$ or US-5654220-\$ or US-5048179-\$).did.	US-PGPUB; USPAT	OR	ON	2007/09/14 19:56
S48	2	(US-5081562-\$ or US-5042145-\$). did.	USPAT	OR	ON	2007/09/14 19:56
S49	9	S46 S47 S48	USPAT	OR	ON	2007/09/14 19:56

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S50	14	S46 S47 S48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 19:57
S51	11	(US-20030068877-\$ or US-20030067074-\$ or US-20030159852-\$ or US-20040000710-\$).did. or (US-5081562-\$ or US-5042145-\$ or US-6806428-\$ or US-5985693-\$ or US-5840593-\$ or US-5654220-\$ or US-5048179-\$).did.	US-PGPUB; USPAT	OR	ON	2007/09/14 19:59
S52	7	S51 and adhesi\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 19:59
S53	6	S52 and insulat\$3 and conduct\$3 and recess\$3 and pattern\$3 and circuit near2 board and embed\$4 and adhesi\$4 and (layer or film or sheet)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:54
S54	6	S52 and insulat\$3 and conduct\$3 and recess\$3 and pattern\$3 and circuit near2 board and embed\$4 and adhesi\$4 and (layer or film or sheet) and (holes or through adj hole)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 20:05
S55	2	S52 and insulat\$3 and conduct\$3 and recess\$3 and pattern\$3 and circuit near2 board and embed\$4 and adhesi\$4 and (layer or film or sheet) and (holes or through adj hole) and (copper or Cu) and (polymer or resin) and drill\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 07:16
S56	4	("6379998").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/14 20:44

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S57	109	S2 and insulat\$3 and conduct\$3 and recess\$3 and pattern\$3 and (circuit near2 board or circuitboard or PCB or motherboard or mother adj board) and embed\$4 and fill\$3 and (holes or through adj hole) and (copper or Cu) and (polymer or resin) and (face or surface or side)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 20:50
S58	90	S57 and (embed\$4 same (chip or component or device or module or microcircuit or micro adj circuit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 20:53
S59	75	S58 and adhesiv\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 20:54
S60	1	S59 and (NOT S33)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/14 20:55
S61	11	(US-20030068877-\$ or US-20030067074-\$ or US-20030159852-\$ or US-20040000710-\$).did. or (US-5081562-\$ or US-5042145-\$ or US-6806428-\$ or US-5840593-\$ or US-5985693-\$ or US-5654220-\$ or US-5048179-\$).did.	US-PGPUB; USPAT	OR	ON	2007/09/17 06:32
S62	1	(US-5042145-\$).did.	USPAT	OR	ON	2007/09/17 06:42
S63	1	S62 and card	USPAT	OR	ON	2007/09/17 06:42
S64	24024	438/15,25,55,64,106,118,618.ccls. or 257/81,700,e33.056,e33.066, e23.001,e23.067.ccls. or 216/13,17, 18.ccls. or 174/261,262,254-256. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:51

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S65	17619	S64 and @ad<"20030918"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:51
S66	919	S65 and IC near3 mount\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:51
S67	241	S66 and \$5conduct\$3 and insulat\$3 and fill\$3 and adhesi\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:52
S68	197	S67 and (holes or through adj hole)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:52
S69	65	S68 and recess\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:53
S70	62	S69 and pattern\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 06:54
S71	2	("6984591").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/17 07:17

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S72	2	S71 and metal\$3 and film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 07:18
S73	24024	438/15,25,55,64,106,118,618.ccls. or 257/81,700,e33.056,e33.066, e23.001,e23.067.ccls. or 216/13,17, 18.ccls. or 174/261,262,254-256. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 09:54
S74	17619	S73 and @ad<"20030918"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 11:44
S75	919	S74 and IC near3 mount\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 09:54
S76	241	S75 and \$5conduct\$3 and insulat\$3 and fill\$3 and adhesi\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 09:54
S77	197	S76 and (holes or through adj hole)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 11:43
S78	65	S77 and recess\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 11:43

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S79	62	S78 and pattern\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 11:42
S80	37	S79 and (multi adj layer or multilayer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 10:08
S81	4518	S74 and (multi adj layer or multilayer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 11:42
S83	247	S74 and (holes or through adj hole) and recess\$3 and pattern\$3 and (multi adj layer or multilayer) and \$5conduct\$3 and insulat\$3 and fill\$3 and adhesi\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/17 12:20
S84	2	("20030159852").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/17 15:26